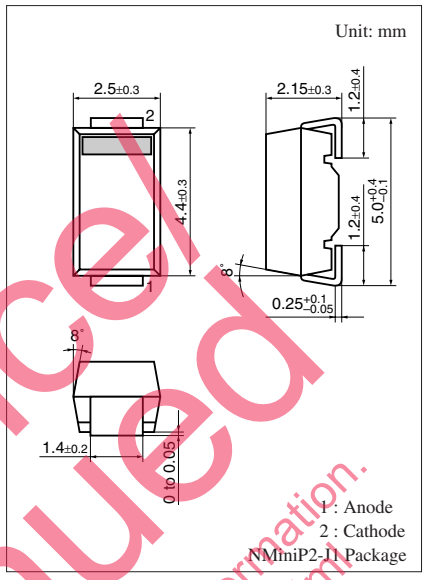
MA2Q735 (MA735)

Silicon epitaxial planar type

For high frequency rectification



Marking Symbol: PA

■ Features

- Forward current (Average) $I_{F(AV)}$ = 1 A rectification is possible
- Reverse voltage V_R = 30 V is guaranteed
- Automatic insertion with the emboss taping is possible

■ Absolute Maximum Ratings T_a = 25°C

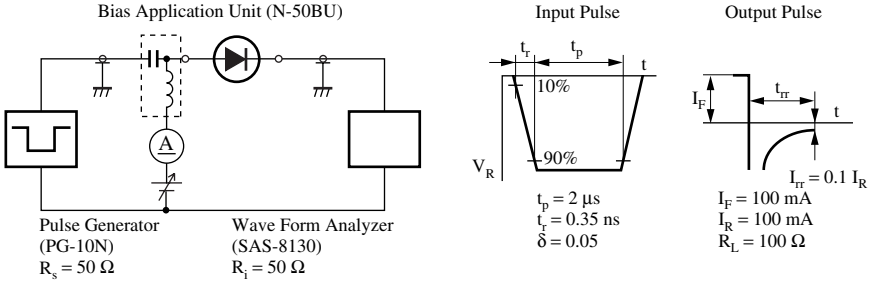
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Maximum peak reverse voltage	V_{RM}	30	V
Forward current (Average) *1	$I_{F(AV)}$	1	A
Non-repetitive peak forward surge current *2	I_{FSM}	30	A
Junction temperature	T_j	−40 to +125	°C
Storage temperature	T_{stg}	−40 to +125	°C

Note) *1: Mounted on the printed circuit board (glass epoxy board)
*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Electrical Characteristics T_a = 25°C ± 3°C

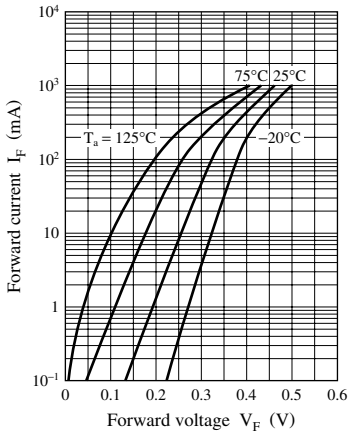
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 1.0 A			0.5	V
Reverse current	I_R	V_R = 30 V			1	mA
Terminal capacitance	C_t	V_R = 10 V, f = 1 MHz		50		pF
Reverse recovery time *	t_{rr}	I_F = I_R = 100 mA I_{rr} = 0.1 I_R, R_L = 100 Ω			30	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 20 MHz.
4. *: t_{rr} measurement circuit

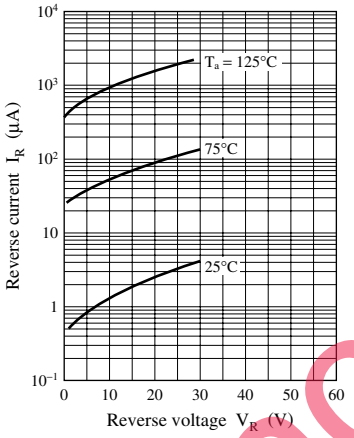


Note) The part number in the parenthesis shows conventional part number.

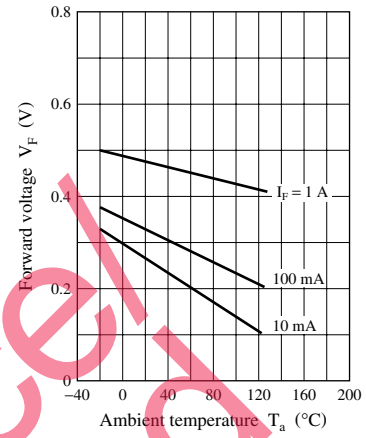
I_F — V_F



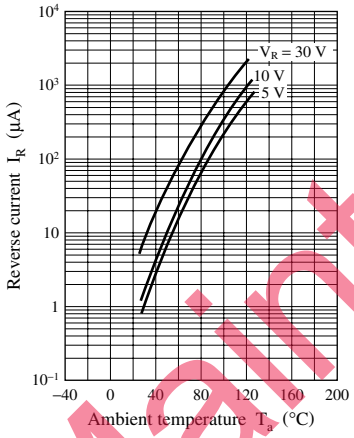
I_R — V_R



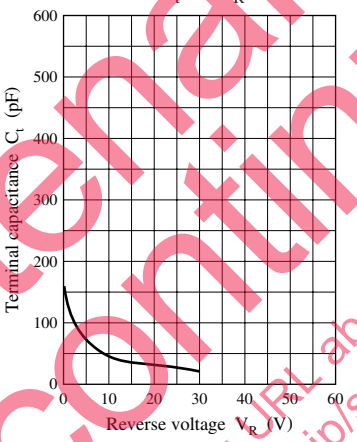
V_F — T_a



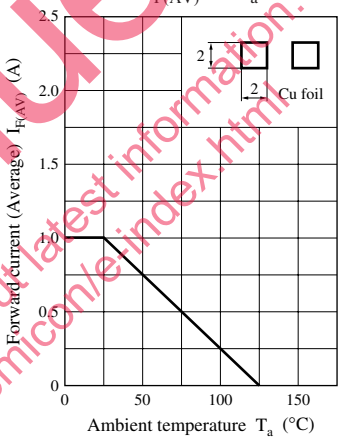
I_R — T_a



C_t — V_R



$I_{F(AV)}$ — T_a



Request for your special attention and precautions in using the technical information and semiconductors described in this material

(1) An export permit needs to be obtained from the competent authorities of the Japanese Government if any of the products or technical information described in this material and controlled under the "Foreign Exchange and Foreign Trade Law" is to be exported or taken out of Japan.

(2) The technical information described in this material is limited to showing representative characteristics and applied circuits examples of the products. It neither warrants non-infringement of intellectual property right or any other rights owned by our company or a third party, nor grants any license.

(3) We are not liable for the infringement of rights owned by a third party arising out of the use of the technical information as described in this material.

(4) The products described in this material are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).
Consult our sales staff in advance for information on the following applications:
- Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
- Any applications other than the standard applications intended.

(5) The products and product specifications described in this material are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.

(6) When designing your equipment, comply with the guaranteed values, in particular those of maximum rating, the range of operating power supply voltage, and heat radiation characteristics. Otherwise, we will not be liable for any defect which may arise later in your equipment.
Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.

(7) When using products for which damp-proof packing is required, observe the conditions (including shelf life and amount of time let standing of unsealed items) agreed upon when specification sheets are individually exchanged.